

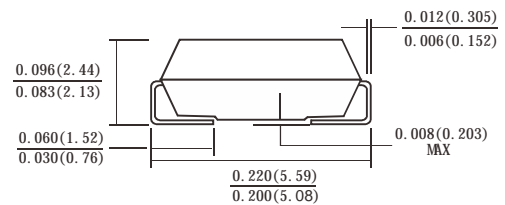
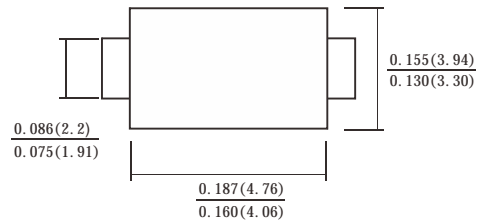


Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junctions
- Fast switching for high efficiency
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SMB(DO-214AA)



Dimensions in inches and (millimeters)

Mechanical Date

- **Case:** JEDEC DO-214AA molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Maximum Ratings and Electrical Characteristics Rating at 25 °C

ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYMBOL	ES3A	ES3B	ES3C	ES3D	ES3E	ES3G	ES3J	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Average Rectified Output Current @ $T_L = 100^\circ C$	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100							A
Forward Voltage @ $I_F = 3.0A$	V_{FM}	1.0			1.25		1.65		V
Peak Reverse Current @ $T_A = 25^\circ C$	I_R	5.0							uA
At Rated DC Blocking Voltage @ $T_A = 125^\circ C$		100							
$I^2 t$ Rating for fusing ($t < 8.3ms$)	$I^2 t$	26.56							A^2s
Maximum Reverse Recovery Time (Note 1)	T_{rr}	35							ns
Typical Junction Capacitance (Note 2)	C_J	45							pF
Typical Thermal Resistance Junction to Ambient(Note 3)	$R_{\theta JA}$	20							$^\circ C/W$
Operating Temperature Range	T_J	-55 to +150							$^\circ C$
Storage Temperature Range	T_{STG}	-55 to +150							$^\circ C$

Note: 1.Reverse Recovery Test Conditions: $I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A$.

2. Measured at 1.0 MHz and Applied reverse Voltage of 4.0V D.C.

3. Thermal Resistance from Junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas.



Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1 MAXIMUM AVERAGE FORWARD CURRENT DERATING

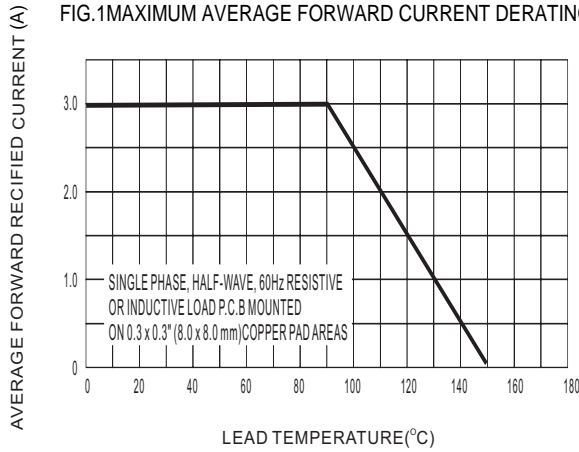


FIG.2 TYPICAL FORWARD CHARACTERISTICS

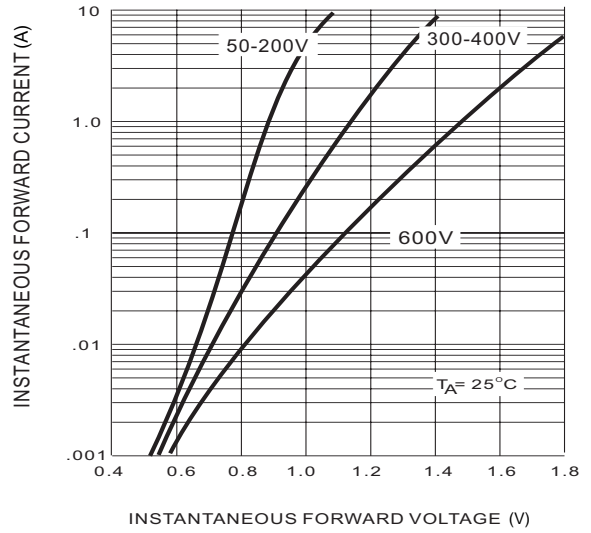


FIG.3 MAXIMUM NON-REPEITIVE SURGE CURRENT

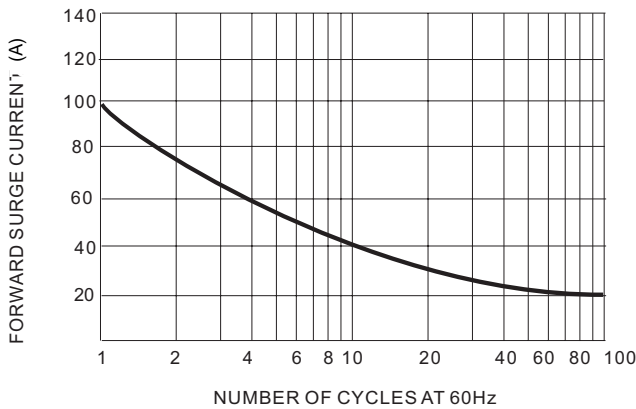


FIG.4 TYPICAL JUNCTION CAPACITANCE

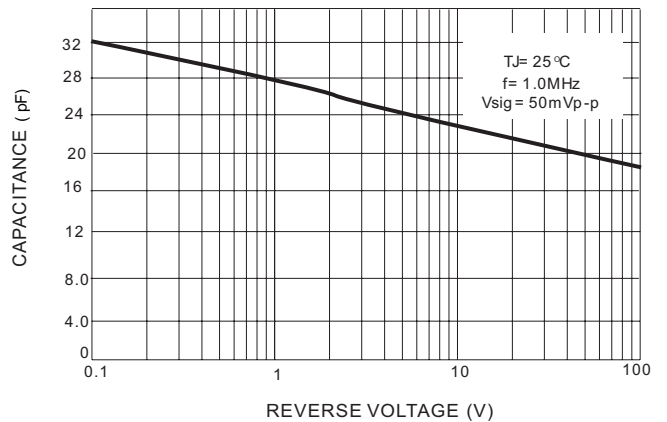


FIG.5 TYPICAL REVERSE CHARACTERISTICS

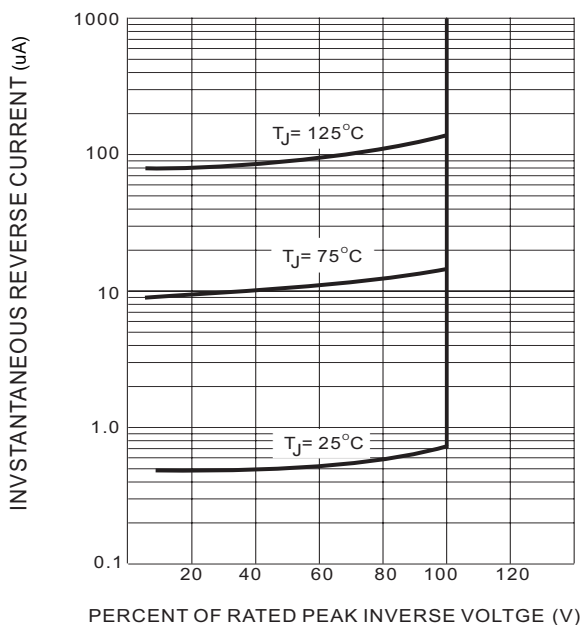


FIG.6 MOUNTING PAD LAYOUT

